Standardized Information for Process/Product Change Notification (PCN)

Form provided by ZVEI - Revision 3.0.0

1. PCN basic data		
1.1 Company	TAIWAN SEMICONDUCTOR	
1.2 PCN No.	PCN20003	
1.3 Title of PCN	Micro SMA plating process Improvement from Barrel to Strip plating	
1.4 Product Category	Active Components - Discrete Components	
1.5 Issue date	2020/02/06	
1.6 PCN revision history (optional)	1.7 Issue date of previous revision (optional)	1.8 Delta to previous revision (optional)

2. PCN Team		
2.1 Contact supplier		
2.1.1 Name	Sunnie Lin	
2.1.2 Phone	+886-2-8913-1588 Ext:2205	
2.1.3 Email	sunnie.lin@mail.ts.com.tw	
2.2 Team supplier (optional)		
2.2.1 Name (optional)	2.2.2 Phone (optional)	2.2.3 Email (optional)
Chun Chen	+886-3-928-5017 Ext.:320	chun@mail.ts.com.tw
Eason Yang	+886-3-928-5017 Ext.:118	eason@mail.ts.com.tw
CK Lin	+886-3-928-5017 Ext.:308	ck.lin@mail.ts.com.tw
Ken Kan	+886-2-8913-1588 Ext:2103	Ken_Kan@mail.ts.com.tw

3. Changes			
No.	3.0 Ident	3.1 Category	3.2 Type of change
#1	SEM-PA-14	PROCESS - ASSEMBLY	Change in process technology (e.g. sawing, die attach, bonding, moulding, plating, trim and form, lead frame preperation, …)
#2	SEM-PA-16	PROCESS - ASSEMBLY	Change of direct material supplier
#3	SEM-EQ-01	EQUIPMENT	Production from a new equipment/tool which uses a different basic technology or which due to its unique form or function can be expected to influence the integrity of
#4			
#5			

4. Description of change		
	Old	New
Change #1	Assembly process: Molding --> PMC --> DeFlash --> TF + DeGate --> Reflow --> Plating --> TMTT	Assembly process: Molding --> DeGate --> PMC --> Reflow --> Plating --> TF --> TMTT
Change #2	Plating process: Barrel Plating	Plating process: Strip Plating
Change #3	Plating thickness: 5~20um	Plating thickness: 8~20um
Change #4	Plating supplier: Supplier A	Plating supplier: Supplier B
Change #5		
4.6 Anticipated impact on form, fit, function, reliability or processability?	The qualification plan was according to ZVEI and the verification passed.	

4.7 Reference parts with customer number (optional)	

5. Reason / motivation for change	
5.1 Motivation	Improve plating uniformity
5.2 Additional explanation (optional)	

6. Marking of parts / traceability of change	
6.1 Description	Use datecode control

7. Timing / schedule		
7.1 Date of qualification results	2019/09/06	
7.2 Last order date (optional)	2020/08/04	
7.3 Last delivery date (optional)	2021/08/04	
7.4 Intended start of delivery	2020/08/04	
7.5 Qualification samples available?	Can be submitted 1 month upon receipt of customer order	
7.6 Customer feedback required until	2020/03/22	

8. Qualification / validation				
8.1 Description (e.g. qual. plan/report, AEC-Q...)	According to AEC-Q101			
8.2 Qualification report and qualification results	available (see attachement)	issue date	2019/09/06	

9. Input to customer for risk assessment process
Equipment : Mid Risk Technique-Wafer : Low Risk Technique-Assembly : Low Risk Sample submit time : within 30 days Form/ Fit / Function : Low Risk Reliability : Low Risk

10. Attachments (e.g. new datasheet, additional documentation, pictures, process flow, sample plan, ...)
Refer to the official e-mail announcement for the applicable documents.

11. Affected parts									
11.1 Current						11.2 New (if applicable)			
11.1.1 Customer Part No.	11.1.2 Supplier Part Name	11.1.3 Supplier Part No. (optional)	11.1.4 Package Name	11.1.5 Part Description (optional)	11.1.6 Additional Part Information (optional)	11.2.2 Supplier Part Name	11.2.3 Supplier Part No. (optional)	11.2.4 Package Name	11.2.6 Additional Part Information (optional)
